Product-Env-Stewards     Product Enviro Compliance     NA     Product-Env-Stewards       Requester Item Number     Mfr Item Number     Mfr Item Name     Effective Date     Version     Manufacturing Site     Weight*		i.com	
Company name*  Company unique ID  Unique ID Authority  Response Date* 2023-06-08  Contact Name  Title - Contact  Product-Env-Stewards  Authorized Representative*  Product-Env-Stewards  Product-Enviro Compliance  Product-Env-Stewards  Product-Enviro Compliance  Product-Env-Stewards  Product-Enviro Compliance  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*	ards@onsemi.	i.com	
2023-06-08	ards@onsemi.	.com	
Contact Name  Title - Contact  Product-Env-Stewards  Product Enviro Compliance  Authorized Representative*  Title - Representative  Product-Env-Stewards  Product-Enviro Compliance  Phone - Representative*  Phone - Representative*  Phone - Representative*  Phone - Representative*  Product-Env-Stewards  Product-Enviro Compliance  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*	ards@onsemi.	i.com	
Product-Env-Stewards Authorized Representative* Product-Env-Stewards Title - Representative Product-Env-Stewards Product-Env-Stewards Product Enviro Compliance Product-Env-Stewards Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Product-Env-Stewards NA Product-Env-Stewards Weight*	ards@onsemi.	i.com	
Authorized Representative*  Title - Representative  Product-Env-Stewards  Product Enviro Compliance  Requester Item Number  Mfr Item Number  Mfr Item Name  Product-Env-Stewards  Reflective Date  Version  Manufacturing Site  Weight*	ards@onsemi.	.com	
Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight*			
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight*	Email - Representative*		
	Product-Env-Stewards@onsemi.com		
ELYOSOGIA (TAMPY A A D. I. DDD T	UOM	Unit Type	
FAN23SV04TAMPX   4 A Buck DDR Termination   2023-06-08   PBB   83.149	mg	Each	
Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number	per of Reflow C	Zwalac	
	er of Reflow C	Lycies	
Watter Till (Sil) - aimearch CO Anoy 1 200 C 30 Seconds 5			
omments			
ovel 1 - maximum time at peak temperature during soldering is 10-30 seconds or more information regarding material composition please refer to page 3			

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.14	mg	Supplier	Silicon (Si)	7440-21-3		1.14	mg
Die Attach Solder	1.362	mg	Supplier	Silver (Ag)	7440-22-4		0.034	mg
			A	Lead (Pb)	7439-92-1	7a	1.2599	mg
			Supplier	Tin (Sn)	7440-31-5		0.0681	mg
Lead Frame	30.983	mg	Supplier	Silver (Ag)	7440-22-4		0.282	mg
			Supplier	Zinc (Zn)	7440-66-6		0.04	mg
			Supplier	Iron (Fe)	7439-89-6		0.744	mg
			Supplier	Copper (Cu)	7440-50-8		29.917	mg
Mold Compound-Black	46.6	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		4.194	mg
			Supplier	Carbon Black (C)	1333-86-4		0.466	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.008	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.932	mg
Plating	1.78	mg	Supplier	Tin (Sn)	7440-31-5		1.78	mg
Wire Bond - Au	0.684	mg	Supplier	Gold (Au)	7440-57-5		0.684	mg
Wire Bond - Cu	0.6	mg	Supplier	Palladium (Pd)	7440-05-3		0.012	mg
			Supplier	Copper (Cu)	7440-50-8		0.588	mg